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## 1 Maximum ratings

at  $T_A=25\text{ °C}$ , unless otherwise specified

**Table 2 Maximum ratings**

| Parameter                          | Symbol            | Values |      |            | Unit | Note / Test Condition                             |
|------------------------------------|-------------------|--------|------|------------|------|---------------------------------------------------|
|                                    |                   | Min.   | Typ. | Max.       |      |                                                   |
| Continuous drain current           | $I_D$             | -      | -    | 120<br>120 | A    | $T_C=25\text{ °C}$<br>$T_C=100\text{ °C}$         |
| Pulsed drain current <sup>1)</sup> | $I_{D,pulse}$     | -      | -    | 480        | A    | $T_C=25\text{ °C}$                                |
| Avalanche energy, single pulse     | $E_{AS}$          | -      | -    | 1166       | mJ   | $I_D=50\text{ A}$ , $R_{GS}=25\text{ }\Omega$     |
| Gate source voltage                | $V_{GS}$          | -20    | -    | 20         | V    | -                                                 |
| Power dissipation                  | $P_{tot}$         | -      | -    | 375        | W    | $T_C=25\text{ °C}$                                |
| Operating and storage temperature  | $T_j$ , $T_{stg}$ | -55    | -    | 175        | °C   | IEC climatic category;<br>DIN IEC 68-1: 55/175/56 |

## 2 Thermal characteristics

**Table 3 Thermal characteristics**

| Parameter                                                                            | Symbol     | Values |      |      | Unit | Note / Test Condition |
|--------------------------------------------------------------------------------------|------------|--------|------|------|------|-----------------------|
|                                                                                      |            | Min.   | Typ. | Max. |      |                       |
| Thermal resistance, junction - case                                                  | $R_{thJC}$ | -      | 0.3  | 0.4  | K/W  | -                     |
| Thermal resistance, junction - ambient, minimal footprint                            | $R_{thJA}$ | -      | -    | 62   | K/W  | -                     |
| Thermal resistance, junction - ambient, 6 cm <sup>2</sup> cooling area <sup>2)</sup> | $R_{thJA}$ | -      | -    | 40   | K/W  | -                     |
| Soldering temperature, wave and reflow soldering are allowed                         | $T_{sold}$ | -      | -    | 260  | °C   | reflow MSL1           |

<sup>1)</sup> see Diagram 3

<sup>2)</sup> Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm<sup>2</sup> (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

### 3 Electrical characteristics

**Table 4 Static characteristics**

| Parameter                        | Symbol        | Values |            |            | Unit          | Note / Test Condition                                                                                                                                         |
|----------------------------------|---------------|--------|------------|------------|---------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------|
|                                  |               | Min.   | Typ.       | Max.       |               |                                                                                                                                                               |
| Drain-source breakdown voltage   | $V_{(BR)DSS}$ | 100    | -          | -          | V             | $V_{GS}=0\text{ V}$ , $I_D=1\text{ mA}$                                                                                                                       |
| Gate threshold voltage           | $V_{GS(th)}$  | 2.2    | 3          | 3.8        | V             | $V_{DS}=V_{GS}$ , $I_D=270\text{ }\mu\text{A}$                                                                                                                |
| Zero gate voltage drain current  | $I_{DSS}$     | -      | 0.1<br>10  | 7<br>100   | $\mu\text{A}$ | $V_{DS}=100\text{ V}$ , $V_{GS}=0\text{ V}$ , $T_j=25\text{ }^\circ\text{C}$<br>$V_{DS}=100\text{ V}$ , $V_{GS}=0\text{ V}$ , $T_j=125\text{ }^\circ\text{C}$ |
| Gate-source leakage current      | $I_{GSS}$     | -      | 1          | 100        | nA            | $V_{GS}=20\text{ V}$ , $V_{DS}=0\text{ V}$                                                                                                                    |
| Drain-source on-state resistance | $R_{DS(on)}$  | -      | 1.7<br>2.0 | 2.0<br>2.5 | m $\Omega$    | $V_{GS}=10\text{ V}$ , $I_D=100\text{ A}$<br>$V_{GS}=6\text{ V}$ , $I_D=50\text{ A}$                                                                          |
| Gate resistance <sup>1)</sup>    | $R_G$         | -      | 1.3        | 2          | $\Omega$      | -                                                                                                                                                             |
| Transconductance                 | $g_{fs}$      | 124    | 248        | -          | S             | $ V_{DS} >2 I_D R_{DS(on)max}$ , $I_D=100\text{ A}$                                                                                                           |

**Table 5 Dynamic characteristics<sup>1)</sup>**

| Parameter                    | Symbol       | Values |       |       | Unit | Note / Test Condition                                                                               |
|------------------------------|--------------|--------|-------|-------|------|-----------------------------------------------------------------------------------------------------|
|                              |              | Min.   | Typ.  | Max.  |      |                                                                                                     |
| Input capacitance            | $C_{iss}$    | -      | 12000 | 15600 | pF   | $V_{GS}=0\text{ V}$ , $V_{DS}=50\text{ V}$ , $f=1\text{ MHz}$                                       |
| Output capacitance           | $C_{oss}$    | -      | 1810  | 2353  | pF   | $V_{GS}=0\text{ V}$ , $V_{DS}=50\text{ V}$ , $f=1\text{ MHz}$                                       |
| Reverse transfer capacitance | $C_{rss}$    | -      | 80    | 140   | pF   | $V_{GS}=0\text{ V}$ , $V_{DS}=50\text{ V}$ , $f=1\text{ MHz}$                                       |
| Turn-on delay time           | $t_{d(on)}$  | -      | 33    | -     | ns   | $V_{DD}=50\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=100\text{ A}$ ,<br>$R_{G,ext}=1.6\text{ }\Omega$ |
| Rise time                    | $t_r$        | -      | 26    | -     | ns   | $V_{DD}=50\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=100\text{ A}$ ,<br>$R_{G,ext}=1.6\text{ }\Omega$ |
| Turn-off delay time          | $t_{d(off)}$ | -      | 77    | -     | ns   | $V_{DD}=50\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=100\text{ A}$ ,<br>$R_{G,ext}=1.6\text{ }\Omega$ |
| Fall time                    | $t_f$        | -      | 29    | -     | ns   | $V_{DD}=50\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=100\text{ A}$ ,<br>$R_{G,ext}=1.6\text{ }\Omega$ |

**Table 6 Gate charge characteristics<sup>2)</sup>**

| Parameter                          | Symbol        | Values |      |      | Unit | Note / Test Condition                                                        |
|------------------------------------|---------------|--------|------|------|------|------------------------------------------------------------------------------|
|                                    |               | Min.   | Typ. | Max. |      |                                                                              |
| Gate to source charge              | $Q_{gs}$      | -      | 54   | -    | nC   | $V_{DD}=50\text{ V}$ , $I_D=100\text{ A}$ , $V_{GS}=0\text{ to }10\text{ V}$ |
| Gate to drain charge <sup>1)</sup> | $Q_{gd}$      | -      | 34   | 51   | nC   | $V_{DD}=50\text{ V}$ , $I_D=100\text{ A}$ , $V_{GS}=0\text{ to }10\text{ V}$ |
| Switching charge                   | $Q_{sw}$      | -      | 52   | -    | nC   | $V_{DD}=50\text{ V}$ , $I_D=100\text{ A}$ , $V_{GS}=0\text{ to }10\text{ V}$ |
| Gate charge total <sup>1)</sup>    | $Q_g$         | -      | 168  | 210  | nC   | $V_{DD}=50\text{ V}$ , $I_D=100\text{ A}$ , $V_{GS}=0\text{ to }10\text{ V}$ |
| Gate plateau voltage               | $V_{plateau}$ | -      | 4.5  | -    | V    | $V_{DD}=50\text{ V}$ , $I_D=100\text{ A}$ , $V_{GS}=0\text{ to }10\text{ V}$ |
| Output charge <sup>1)</sup>        | $Q_{oss}$     | -      | 213  | 283  | nC   | $V_{DD}=50\text{ V}$ , $V_{GS}=0\text{ V}$                                   |

<sup>1)</sup> Defined by design. Not subject to production test

<sup>2)</sup> See "Gate charge waveforms" for parameter definition

**Table 7 Reverse diode**

| Parameter                             | Symbol        | Values |      |      | Unit | Note / Test Condition                                              |
|---------------------------------------|---------------|--------|------|------|------|--------------------------------------------------------------------|
|                                       |               | Min.   | Typ. | Max. |      |                                                                    |
| Diode continuous forward current      | $I_S$         | -      | -    | 120  | A    | $T_C=25\text{ °C}$                                                 |
| Diode pulse current                   | $I_{S,pulse}$ | -      | -    | 480  | A    | $T_C=25\text{ °C}$                                                 |
| Diode forward voltage                 | $V_{SD}$      | -      | 0.9  | 1.2  | V    | $V_{GS}=0\text{ V}$ , $I_F=100\text{ A}$ , $T_J=25\text{ °C}$      |
| Reverse recovery time <sup>1)</sup>   | $t_{rr}$      | -      | 99   | 198  | ns   | $V_R=50\text{ V}$ , $I_F=I_S$ , $di_F/dt=100\text{ A/}\mu\text{s}$ |
| Reverse recovery charge <sup>1)</sup> | $Q_{rr}$      | -      | 287  | 574  | nC   | $V_R=50\text{ V}$ , $I_F=I_S$ , $di_F/dt=100\text{ A/}\mu\text{s}$ |

<sup>1)</sup> Defined by design. Not subject to production test

## 4 Electrical characteristics diagrams

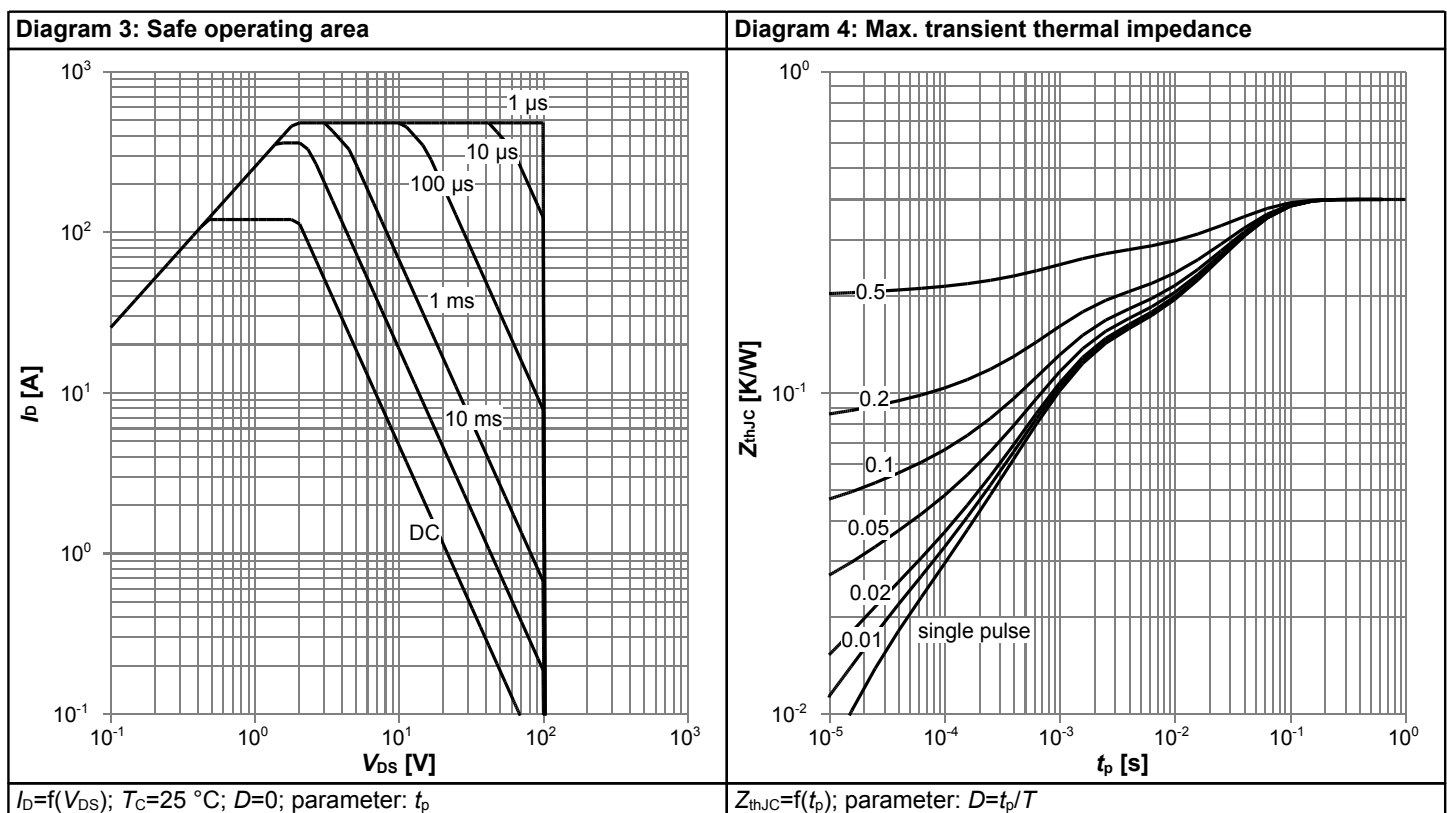
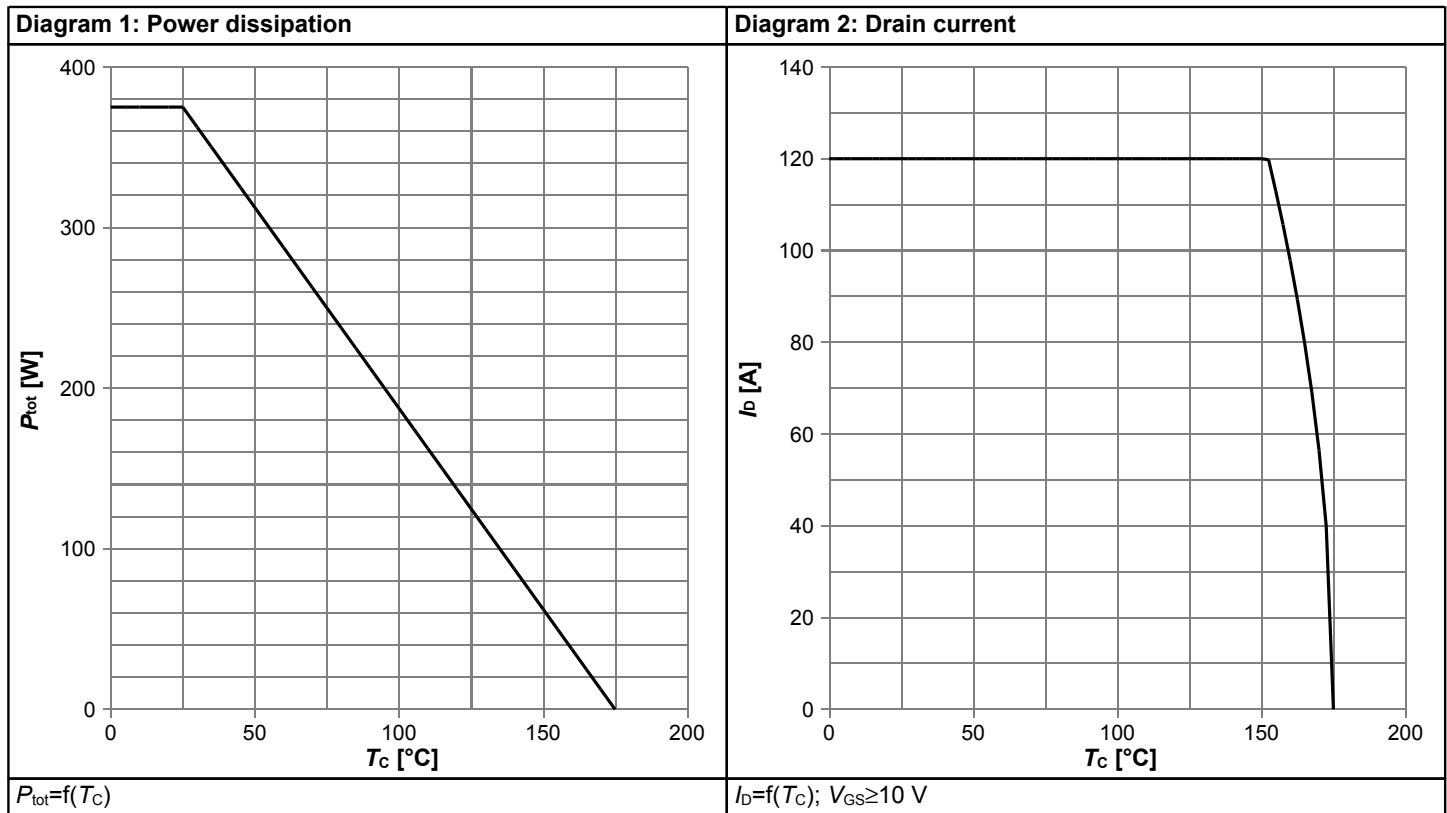
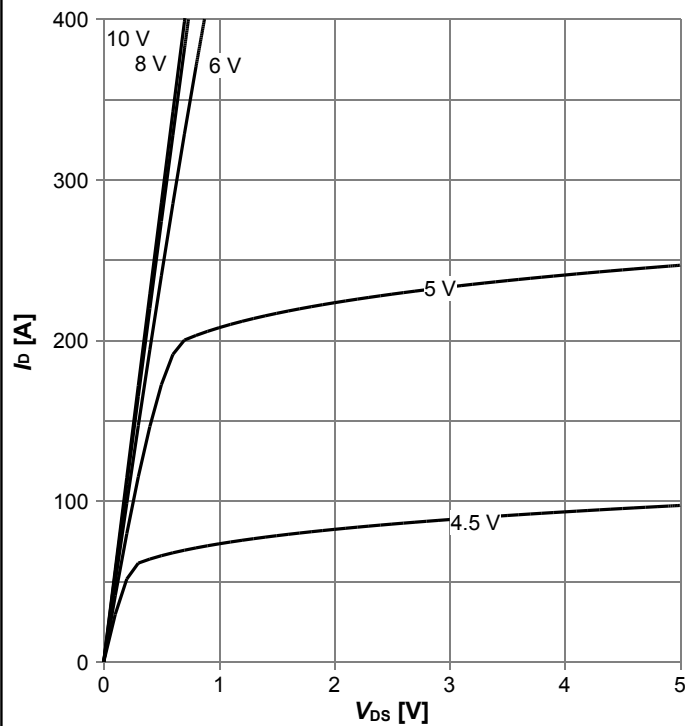
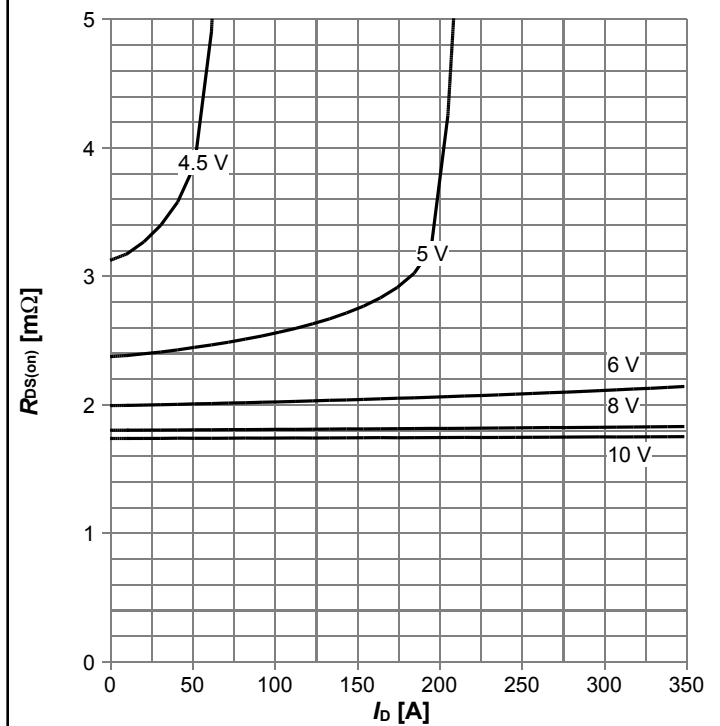


Diagram 5: Typ. output characteristics



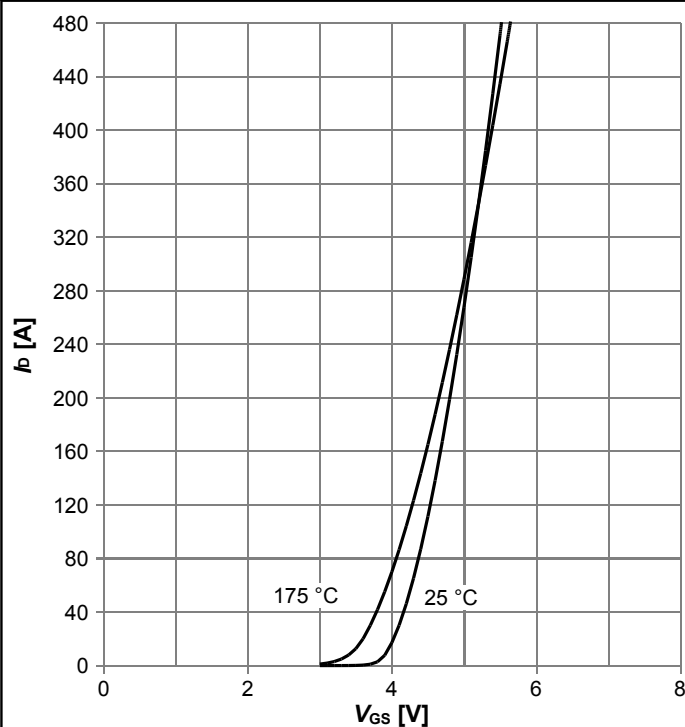
$I_D = f(V_{DS})$ ;  $T_j = 25^\circ\text{C}$ ; parameter:  $V_{GS}$

Diagram 6: Typ. drain-source on resistance



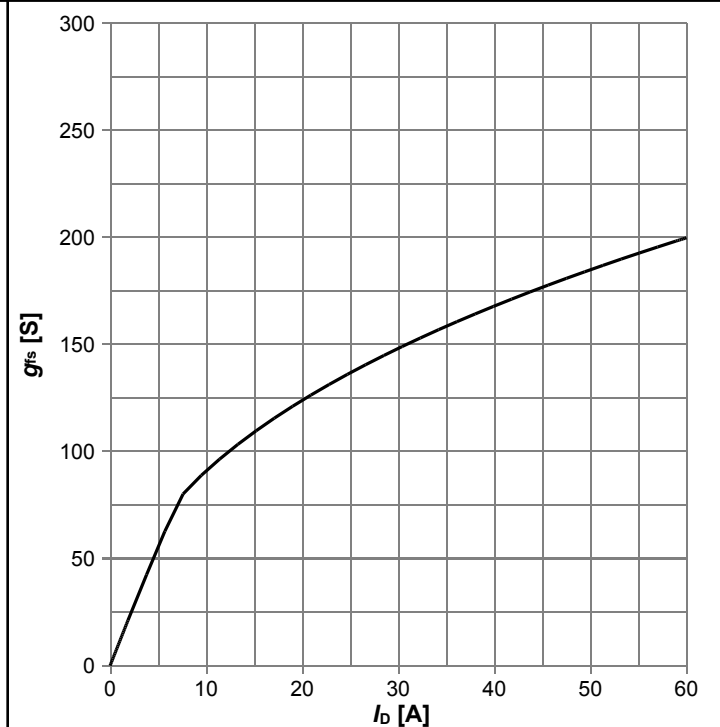
$R_{DS(on)} = f(I_D)$ ;  $T_j = 25^\circ\text{C}$ ; parameter:  $V_{GS}$

Diagram 7: Typ. transfer characteristics



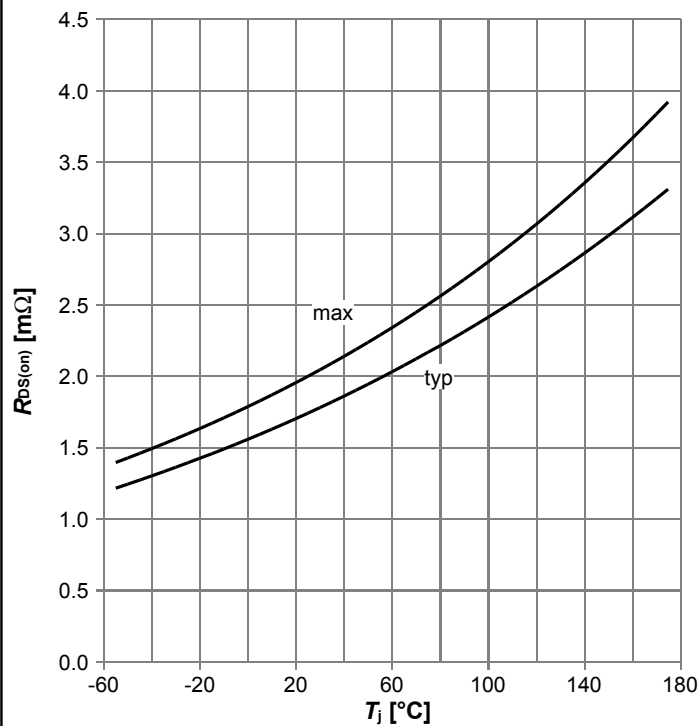
$I_D = f(V_{GS})$ ;  $|V_{DS}| > 2|I_D|R_{DS(on)max}$ ; parameter:  $T_j$

Diagram 8: Typ. forward transconductance



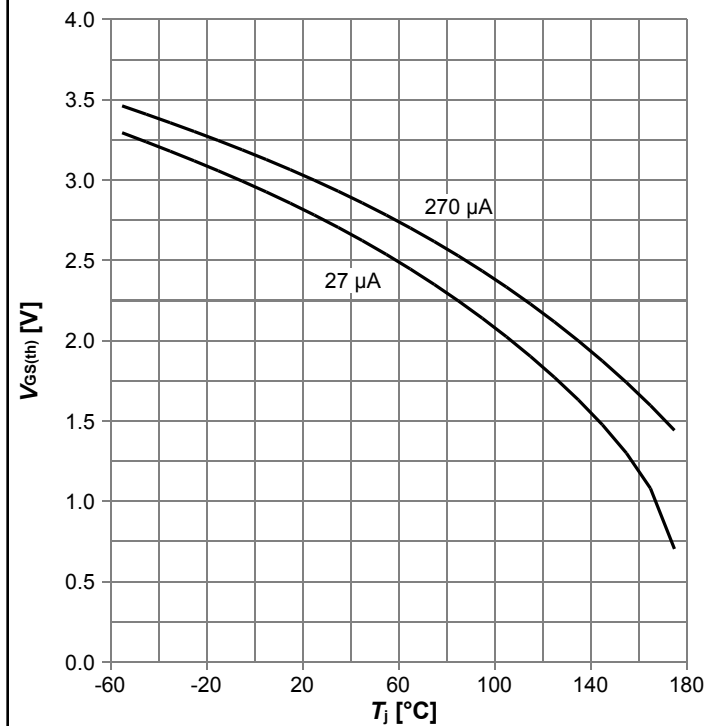
$g_{fs} = f(I_D)$ ;  $T_j = 25^\circ\text{C}$

Diagram 9: Drain-source on-state resistance



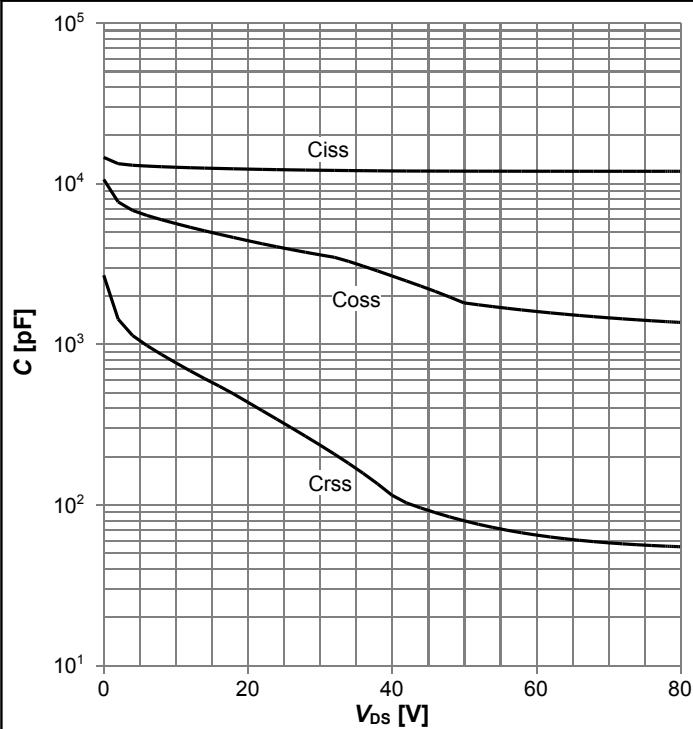
$R_{DS(on)} = f(T_j)$ ;  $I_D = 100 \text{ A}$ ;  $V_{GS} = 10 \text{ V}$

Diagram 10: Typ. gate threshold voltage



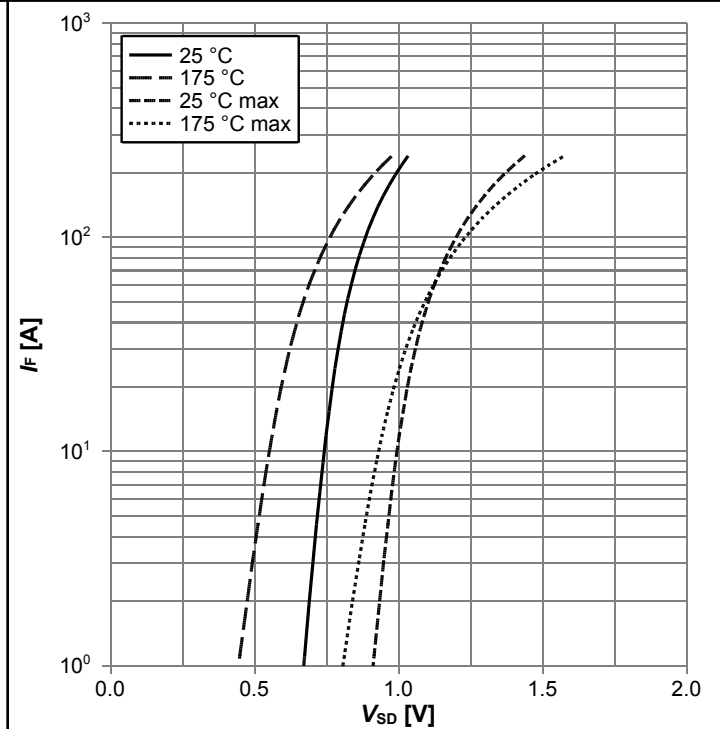
$V_{GS(th)} = f(T_j)$ ;  $V_{GS} = V_{DS}$ ; parameter:  $I_D$

Diagram 11: Typ. capacitances



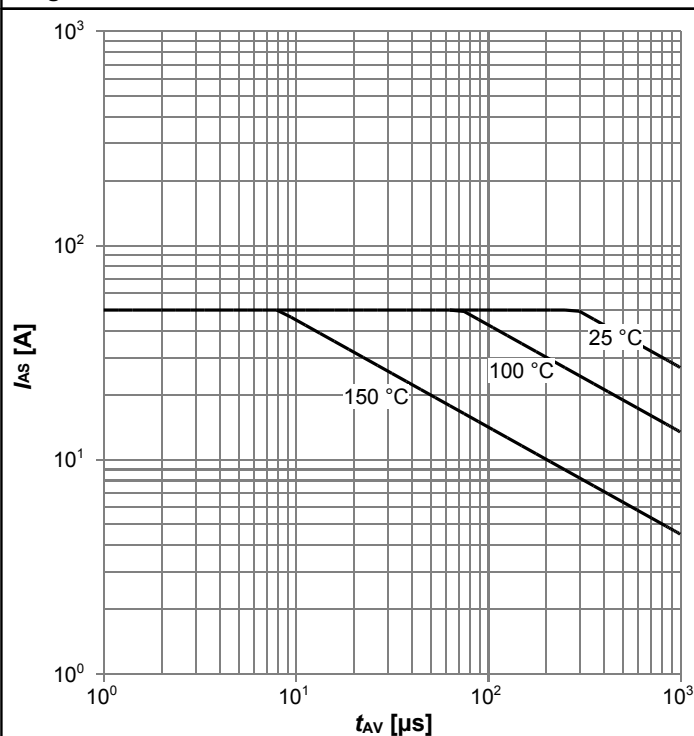
$C = f(V_{DS})$ ;  $V_{GS} = 0 \text{ V}$ ;  $f = 1 \text{ MHz}$

Diagram 12: Forward characteristics of reverse diode



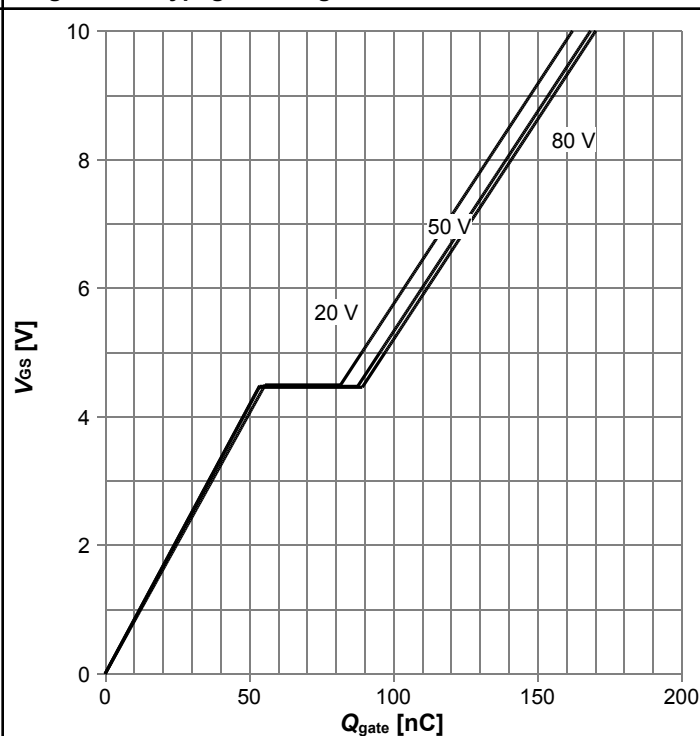
$I_F = f(V_{SD})$ ; parameter:  $T_j$

Diagram 13: Avalanche characteristics



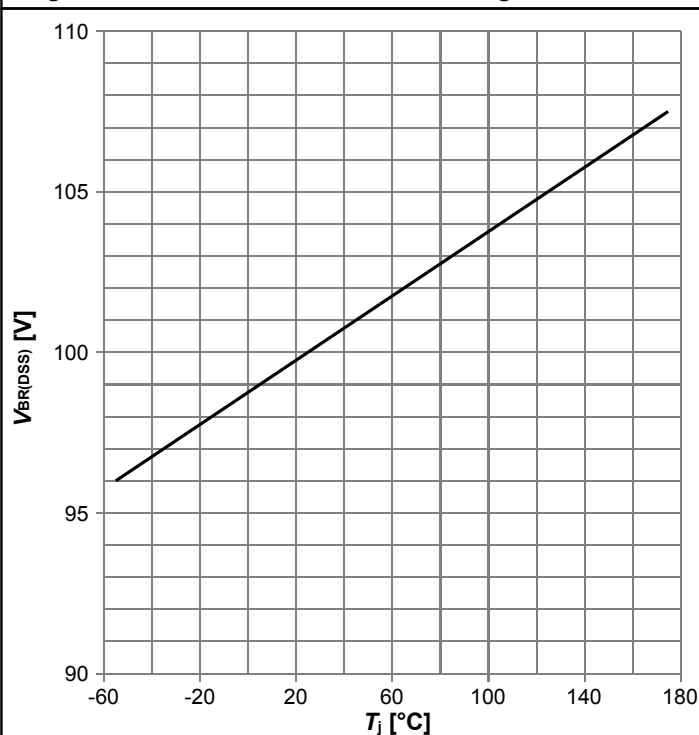
$I_{AS}=f(t_{AV})$ ;  $R_{GS}=25\ \Omega$ ; parameter:  $T_{j(start)}$

Diagram 14: Typ. gate charge



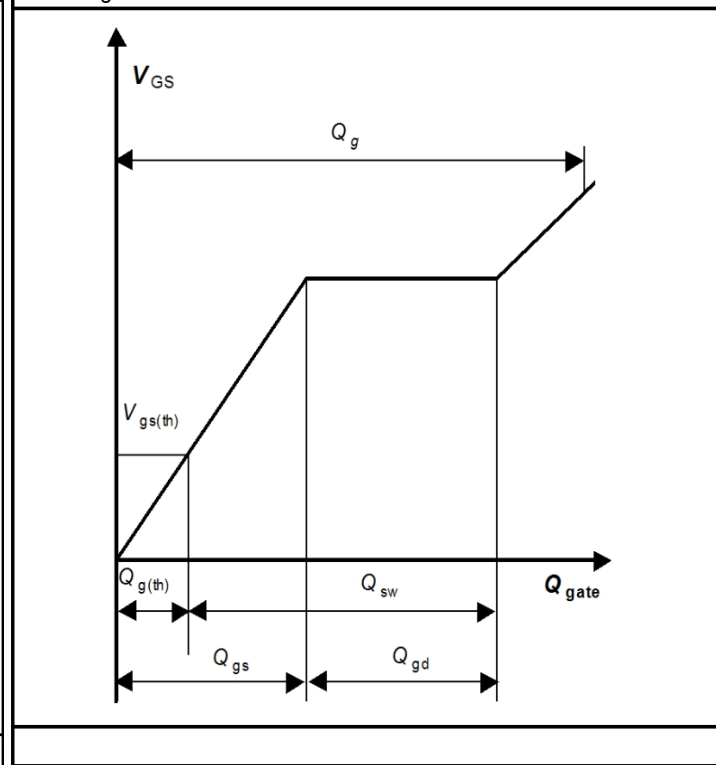
$V_{GS}=f(Q_{gate})$ ;  $I_D=100\text{ A}$  pulsed; parameter:  $V_{DD}$

Diagram 15: Drain-source breakdown voltage



$V_{BR(DSS)}=f(T_J)$ ;  $I_D=1\text{ mA}$

Gate charge waveforms



## 5 Package Outlines

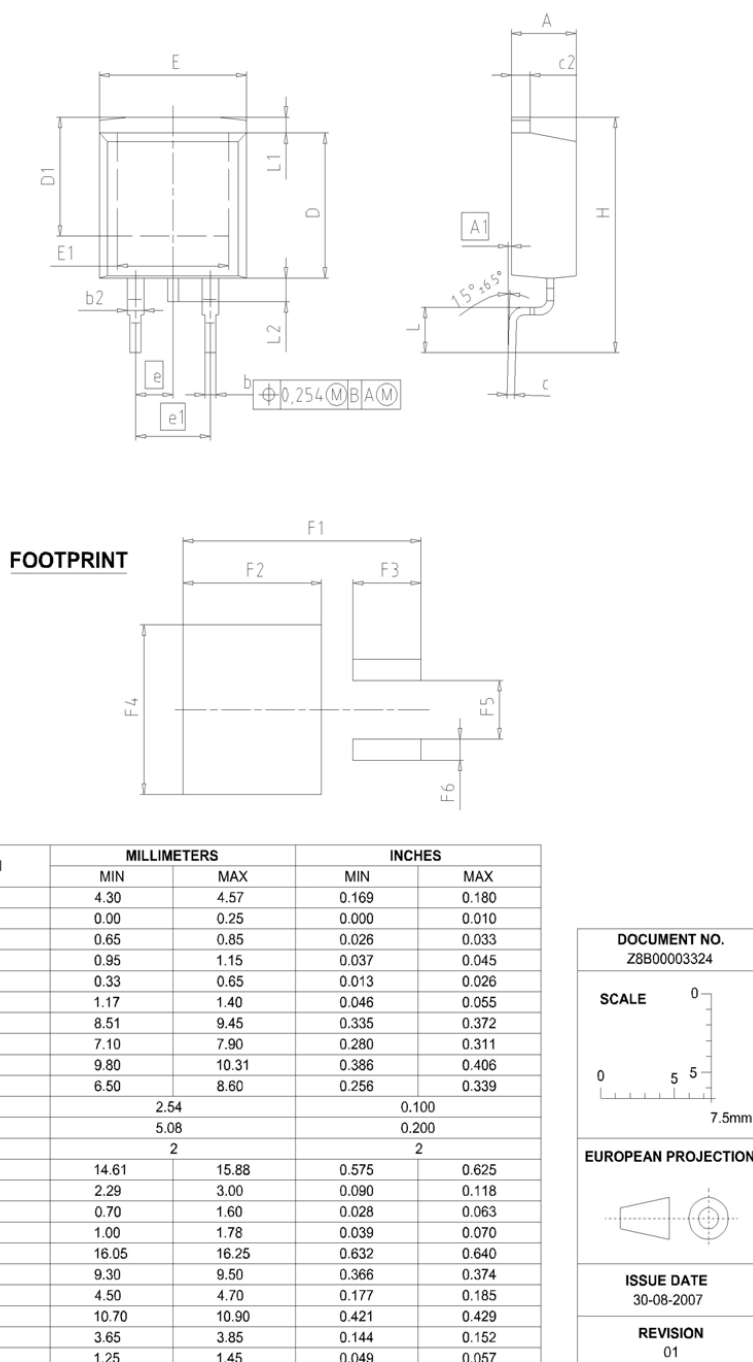


Figure 1 Outline PG-TO 263, dimensions in mm/inches

## Revision History

IPB020N10N5

**Revision: 2016-09-07, Rev. 2.2**

Previous Revision

| Revision | Date       | Subjects (major changes since last revision) |
|----------|------------|----------------------------------------------|
| 2.1      | 2014-05-05 | Release of Final Version                     |
| 2.2      | 2016-09-07 | Update Avalanche Energy                      |

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